## NSN 5962-01-330-5525

Memory Microcircuit - Page 1 of 1



view Online at https://aerobasegroup.com/hsh/5962-01-550-5525
Body Length:
Between 0.554 inches and 0.572 inches
Body Width:
Between 0.554 inches and 0.572 inches
Body Height:
Between 0.055 inches and 0.125 inches
Maximum Power Dissipation Rating:
1.0 watts
Operating Tempurature Range:
-55.0/+125.0 degrees celsius
Storage Tempurature Range:
-65.0/+150.0 degrees celsius
Features Provided:
Hermetically sealed and burn in and static operation and 3-state output
Inclosure Material:
Ceramic
Inclosure Configuration:
Leadless flat pack
Output Logic Form:
Complementary-metal oxide-semiconductor logic
Terminal Surface Treatment:
Solder
Voltage Rating And Type Per Characteristic:
5.0 volts power source
Time Rating Per Chacteristic:
90.00 nanoseconds propagation delay time, low to high level output and 90.00 nanoseconds propagation delay time, high to low level
output
Memory Device Type:
Rom
Test Data Document:
96906-mil-std-883 standard (includes industry or association standards, individual manufactureer standards, etc.).
Terminal Type And Quantity:
48 printed circuit
Shelf Life:
N/a
Unit Of Measure:
Demilitarization:
Yes - demil/mli

Fiig:

A458a0